

# PSR<sup>®</sup>-4000 HS Series

## 放熱対策現像型ソルダーレジスト

### Photoimageable Solder Resist for Heat Spreader

#### 特長 Features

- 熱伝導率が従来の現像型ソルダーレジストの約10倍※(当社比)  
On Thermal conductivity, it is ten times as high as conventional Photoimageable Solder Resist.
- プリント基板の熱拡散が可能  
Heat diffusion of PWB can be performed.



#### 仕様・特性 Specifications & Properties

Test Items	Performance		Remarks/ Test Condition
	PSR <sup>®</sup> -4000 HS Series	PSR <sup>®</sup> -4000 G Series	
色調 Color	White	Green	
露光量 Exposure	700mJ/cm <sup>2</sup>	400 mJ/cm <sup>2</sup>	After Mylar transmission
現像時間 Development	90sec.	60 sec.	1wt% Na <sub>2</sub> CO <sub>3</sub> @30°C
ポストキュア Post Cure	150°C×60min.	150°C×60min.	
ガラス転移点, 線膨張係数 Tg, CTE (α1/α2)	Tg=145°C 25/55 ppm	Tg=100°C 47/134 ppm	α1 / α2
吸水率 Water absorption	0.5%	1.4%	Room temperature 24hr immersion
はんだ耐熱性 Solder heat resistance	Good	Good	260°C×10sec.×3cycles
無電解金めっき耐性 ElectrolessNi/Au plating resistance	Good	Good	Ni 3 μm Au 0.05 μm
解像性 Resolution between QFP pads	80μm	50μm	Thickness 50±3μm
熱伝導性 Thermal conductivity	2.2 W/m·K	0.2 W/m·K	